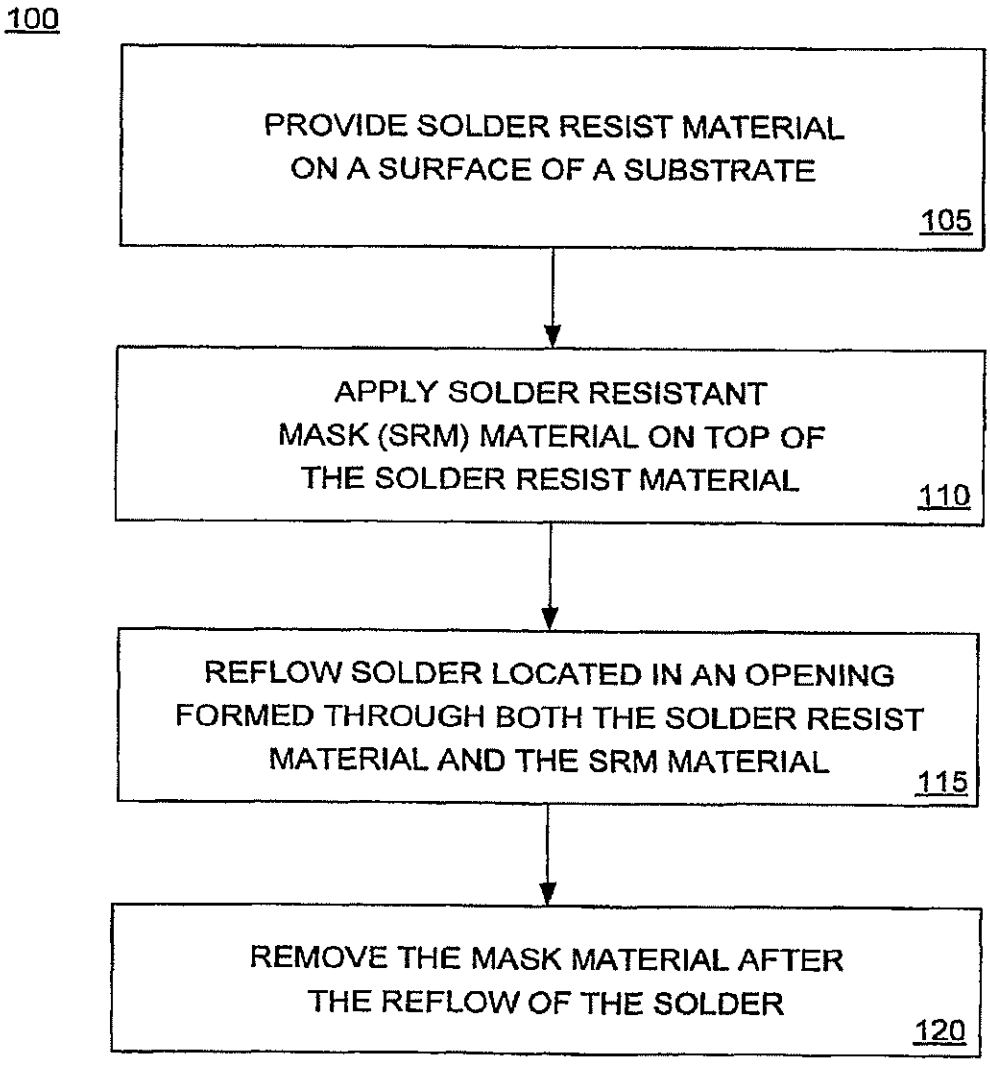

100
PROVIDE SOLDER RESIST MATERIAL ON A SURFACE OF A SUBSTRATE
105
APPLY SOLDER RESISTANT MASK (SRM) MATERIAL ON TOP OF THE SOLDER RESIST MATERIAL
110
REFLOW SOLDER LOCATED IN AN OPENING FORMED THROUGH BOTH THE SOLDER RESIST MATERIAL AND THE SRM MATERIAL
115
REMOVE THE MASK MATERIAL AFTER THE REFLOW OF THE SOLDER
120

FIG. 1

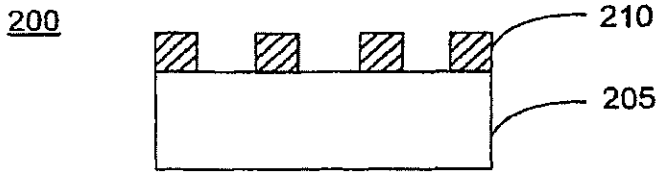


FIG. 2A

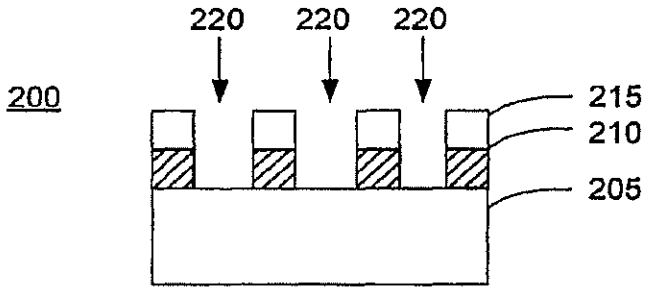


FIG. 2B

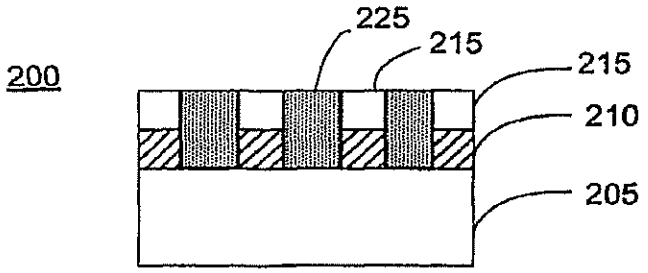


FIG. 2C

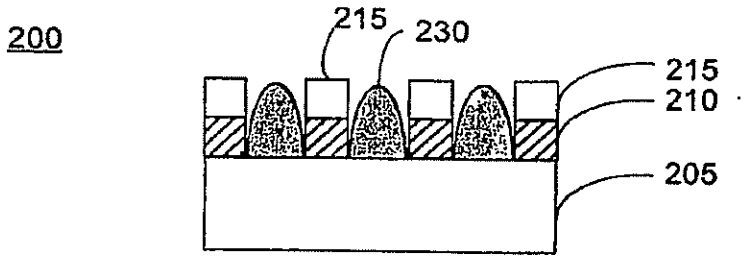


FIG. 2D

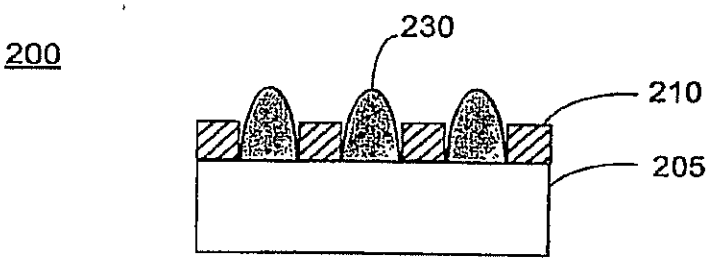


FIG. 2E

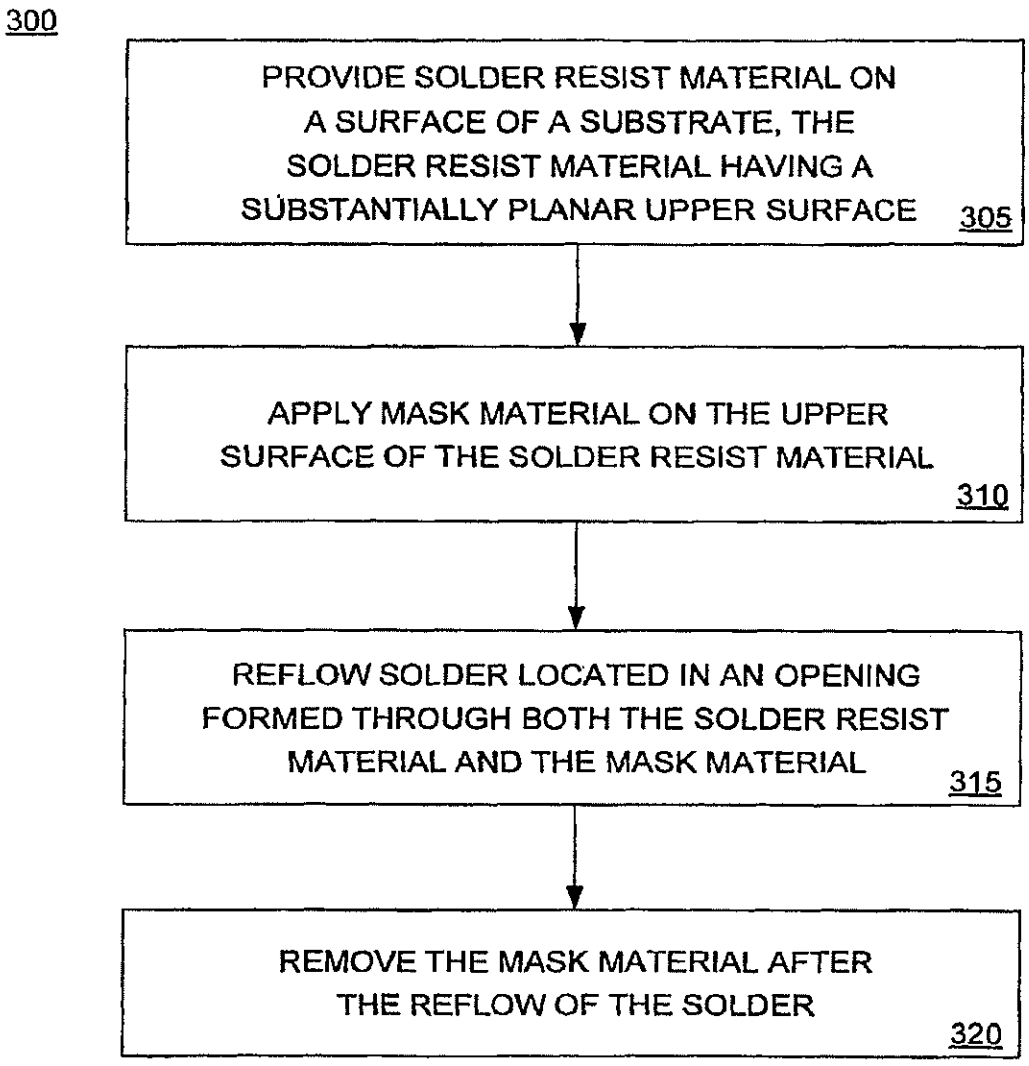

300
PROVIDE SOLDER RESIST MATERIAL ON A SURFACE OF A SUBSTRATE, THE SOLDER RESIST MATERIAL HAVING A SUBSTANTIALLY PLANAR UPPER SURFACE
305
APPLY MASK MATERIAL ON THE UPPER SURFACE OF THE SOLDER RESIST MATERIAL
310
REFLOW SOLDER LOCATED IN AN OPENING FORMED THROUGH BOTH THE SOLDER RESIST MATERIAL AND THE MASK MATERIAL
315
REMOVE THE MASK MATERIAL AFTER THE REFLOW OF THE SOLDER
320

FIG. 3

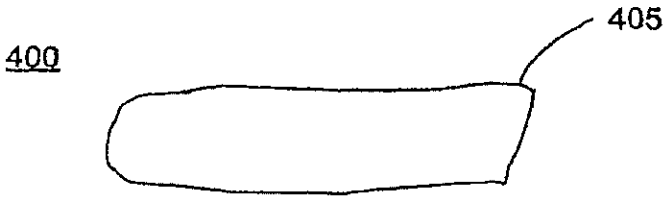


FIG. 4A

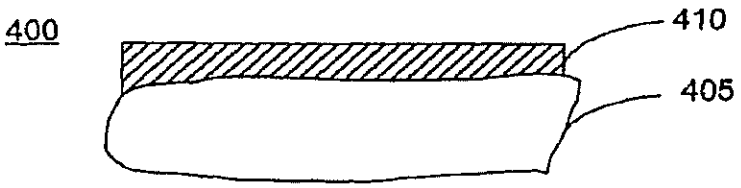


FIG. 4B

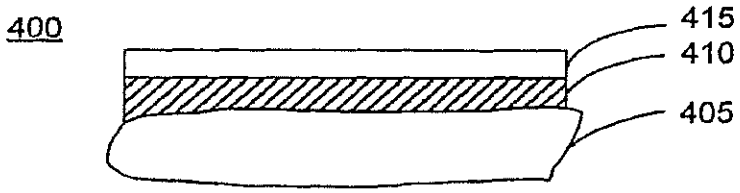


FIG. 4C

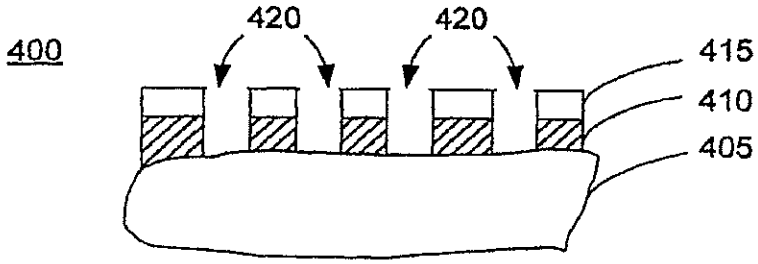


FIG. 4D

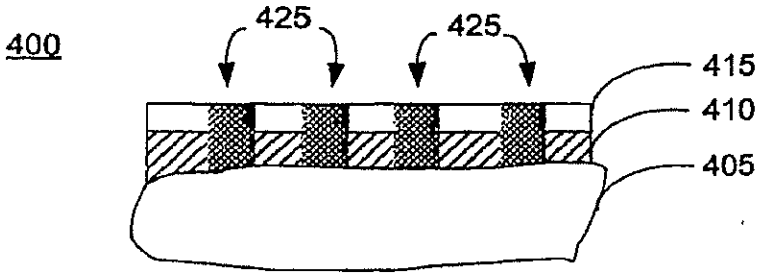


FIG. 4E

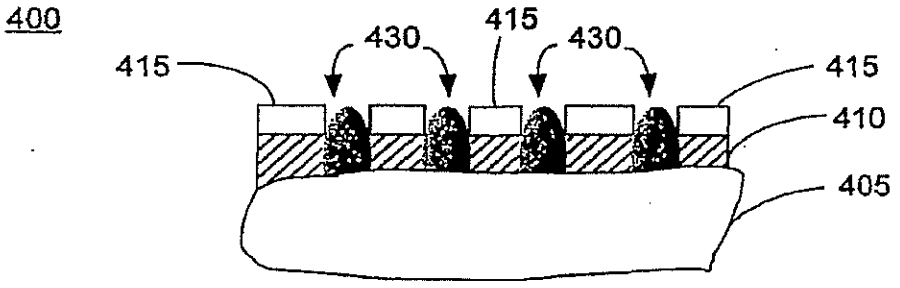


FIG. 4F

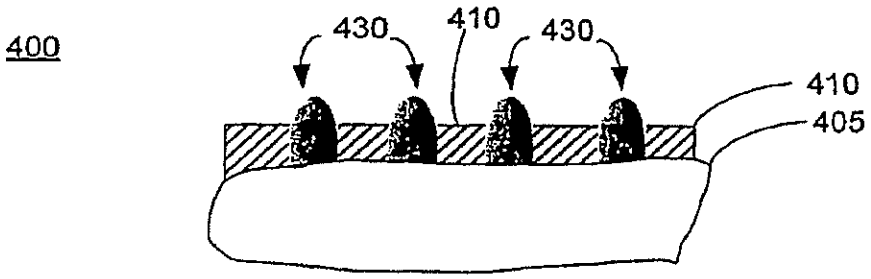


FIG. 4G

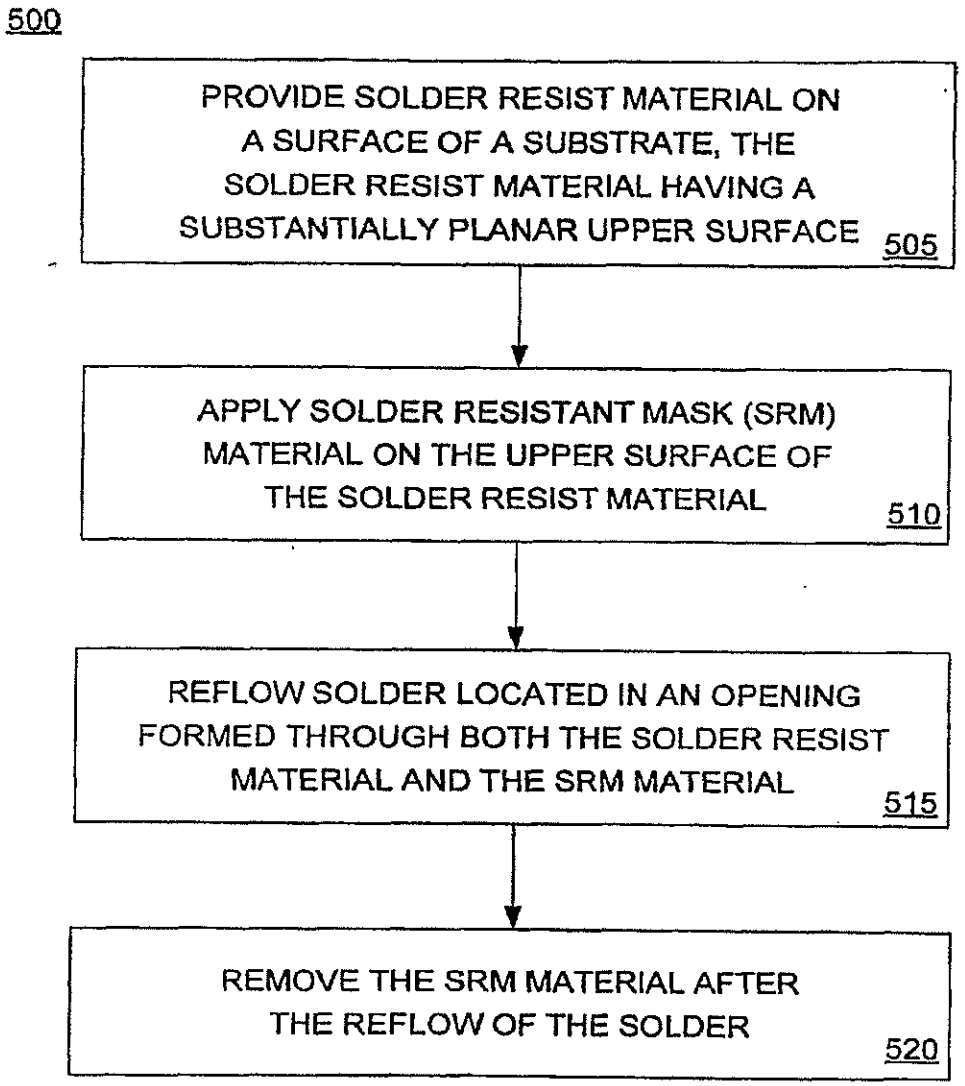

500
PROVIDE SOLDER RESIST MATERIAL ON A SURFACE OF A SUBSTRATE, THE SOLDER RESIST MATERIAL HAVING A SUBSTANTIALLY PLANAR UPPER SURFACE
505
APPLY SOLDER RESISTANT MASK (SRM) MATERIAL ON THE UPPER SURFACE OF THE SOLDER RESIST MATERIAL
510
REFLOW SOLDER LOCATED IN AN OPENING FORMED THROUGH BOTH THE SOLDER RESIST MATERIAL AND THE SRM MATERIAL
515
REMOVE THE SRM MATERIAL AFTER THE REFLOW OF THE SOLDER
520

FIG. 5

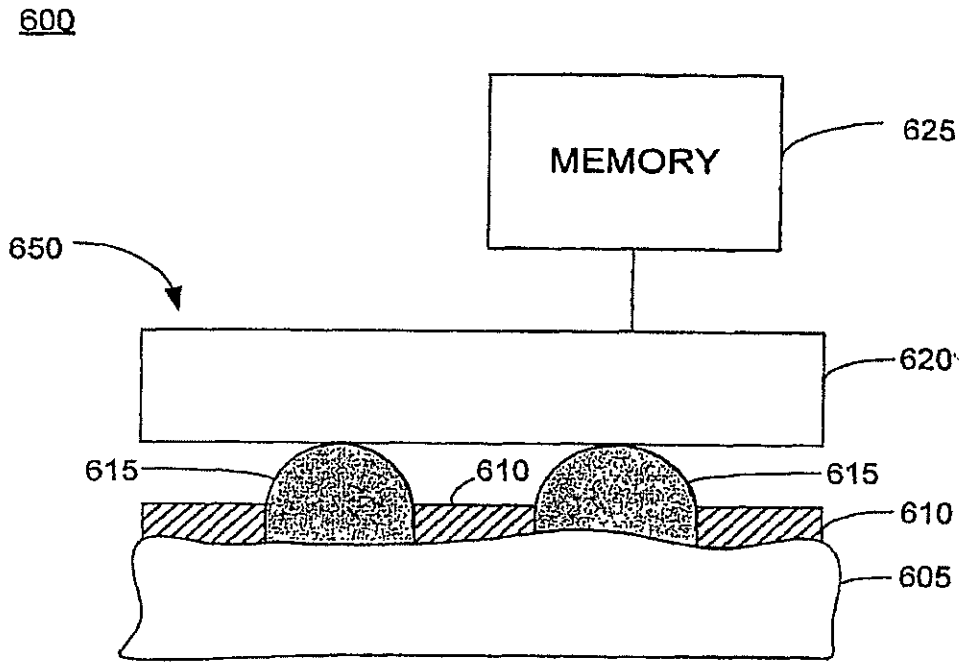


FIG. 6